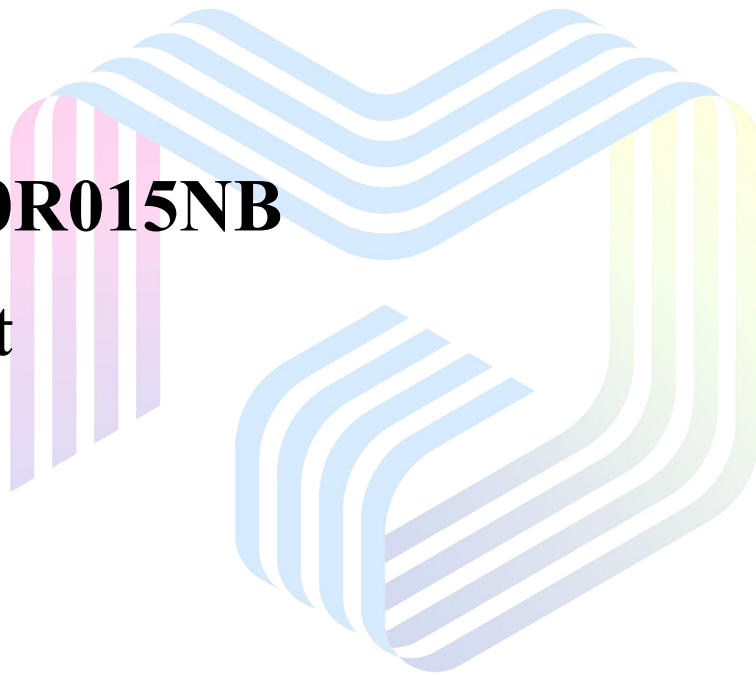


VMDSEMI

**VFTV010R015NB**

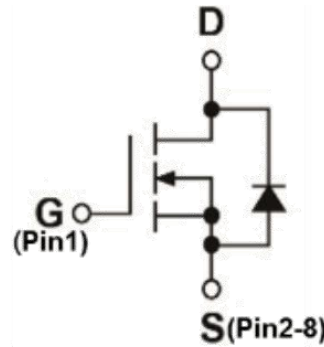
**Datasheet**



VMDSEMI

**1.5mΩ, 100V, N-Channel Power MOSFET**
**VFTV010R015NB**
**General Description**

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
100V	1.5mΩ@10V	330A

**Symbol**


Symbol of VFTV010R015NB

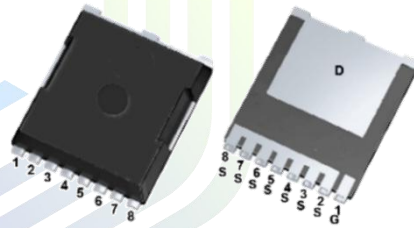
**Features**

- Extremely low  $R_{DS(ON)}$
- Excellent stability and uniformity
- Excellent Low FOM
- 100% EAS Guaranteed

**Package Type**

Top View

Bottom View


**TOLL-8**

Package Type of VFTV010R015NB

**Application**

- BMS
- Switched mode power supply
- Telecom power
- Server power
- LED Backlighting

**Ordering Information**

Product Name	Package
VFTV010R015NB	TOLL-8

**Absolute Maximum Ratings** ( $T_A=25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>Note 1</sup>	$I_D$	$T_C=25^\circ\text{C}$	330
		$T_C=100^\circ\text{C}$	210
Pulsed Drain Current <sup>Note 2</sup>	$I_{D, pulse}$	1320	A
Continuous Diode Forward Current <sup>Note 1</sup>	$I_S$	330	A
Max Power Dissipation <sup>Note 3</sup>	$P_D$	295	W
Avalanche Energy, Single Pulse <sup>Note 4</sup>	$E_{AS}$	2730	mJ
Operation and storage temperature	$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	-	0.498	-	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient <sup>Note 5</sup>	$R_{\theta JA}$	-	31.8	-	

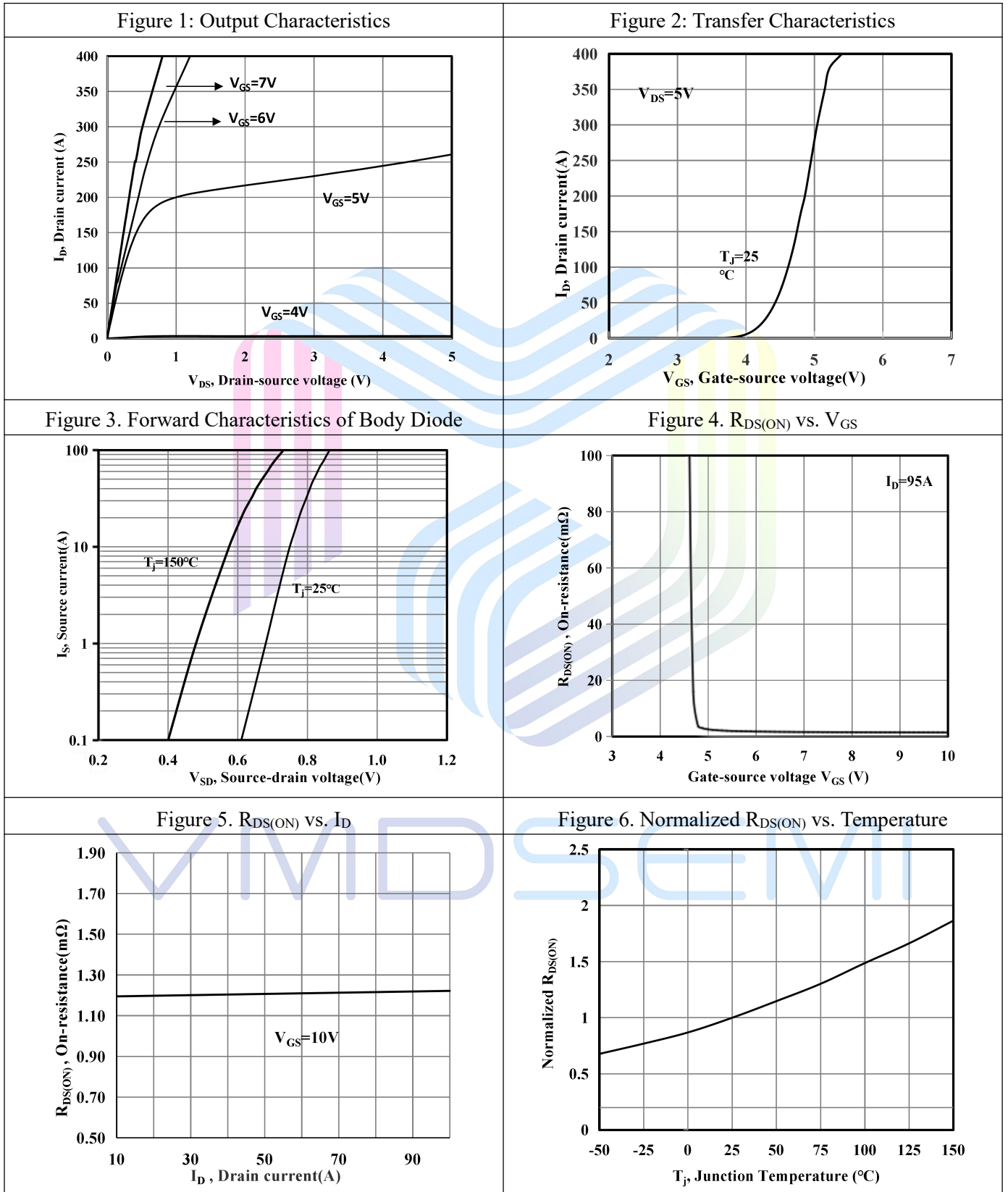
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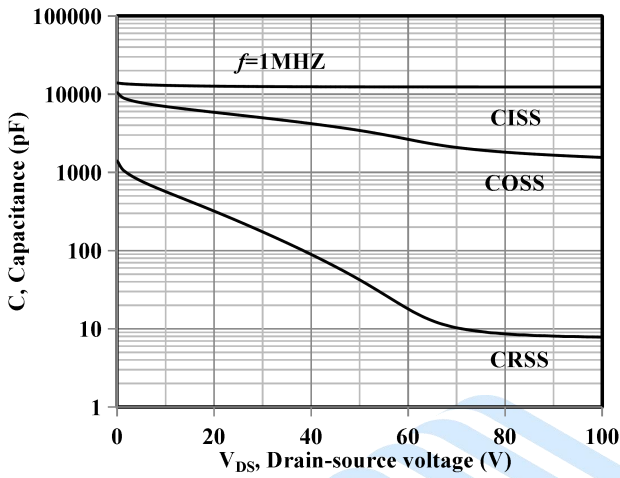
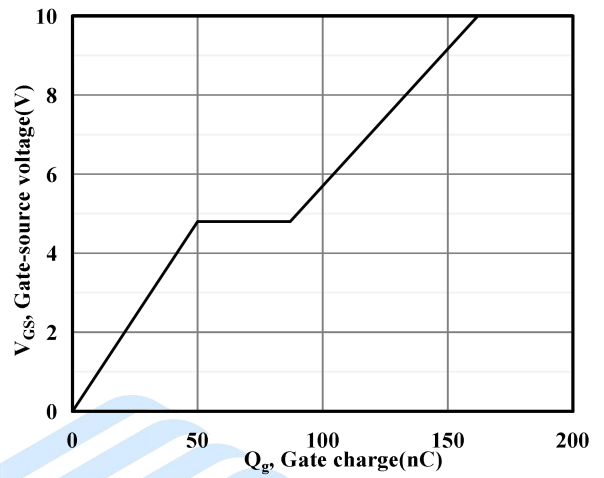
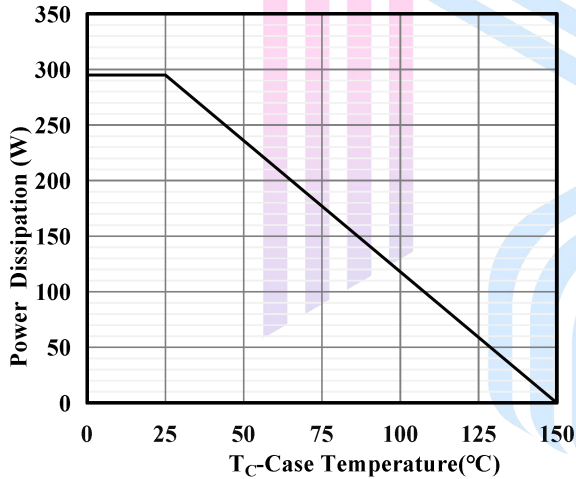
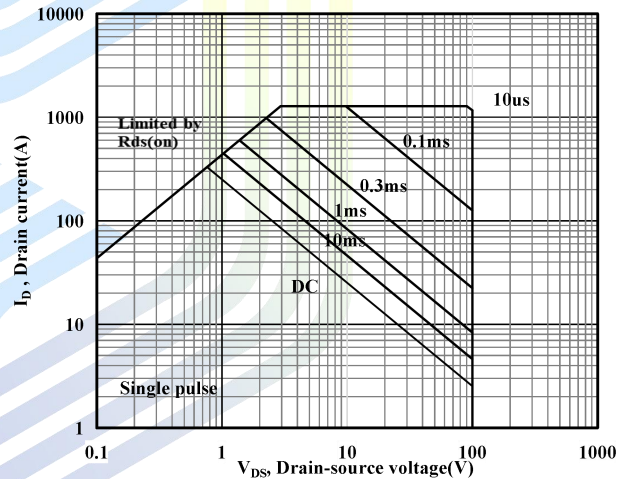
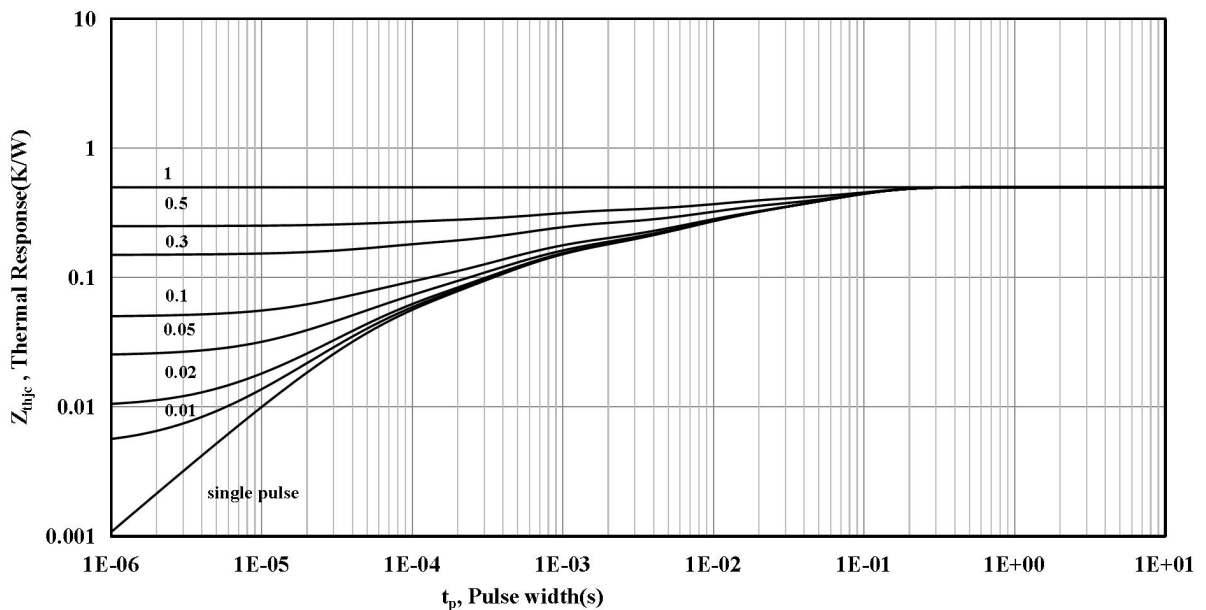
1. Calculated continuous current based on maximum allowable junction temperature.
2. Pulse width limited by safe operating area.
3. Based on max. junction temperature, using junction-case thermal resistance.
4.  $V_{DD}=80\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.5\text{mH}$ , starting  $T_A=25\text{ }^\circ\text{C}$ .
5. When mounted on 1 inch square copper board,  $t \leq 10\text{sec}$ . The value in any given application depends on the user's specific board design.

**Electrical Characteristics** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=100V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Source Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$	-	-	100	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$	-	-	-100	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3	4	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=95A$	-	1.2	1.5	mΩ
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=50V$	-	12425	-	pF
Output Capacitance	$C_{oss}$	$V_{GS}=0V$	-	3385	-	pF
Reverse Transfer Capacitance	$C_{rss}$	$f=1MHz$	-	41	-	pF
Gate Resistance	$R_G$	$F=1MHz, \text{Open Drain}$	-	1.9	-	Ω
Gate to Source Charge	$Q_{gs}$	$V_{DS}=50V$	-	50	-	nC
Gate to Drain Charge	$Q_{gd}$	$I_D=95A$	-	37	-	
Gate Charge Total	$Q_g$	$V_{GS}=10V$	-	162	-	
<b>Switching Characteristics</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=50V$	-	51	-	ns
Rise Time	$t_r$	$I_D=20A$	-	67	-	
Turn-off Delay Time	$t_{d(off)}$	$R_G=2.7\Omega$	-	121	-	
Fall Time	$t_f$	$V_{GS}=10V$	-	39	-	
<b>Reverse Diode Characteristics</b>						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=95A$	-	0.87	1.2	V
Reverse Recovery Time	$t_{rr}$	$V_R=50V$	-	104	-	ns
Reverse Recovery Charge	$Q_{rr}$	$I_S=20A$ $di/dt=100A/\mu s$	-	294	-	$\mu C$

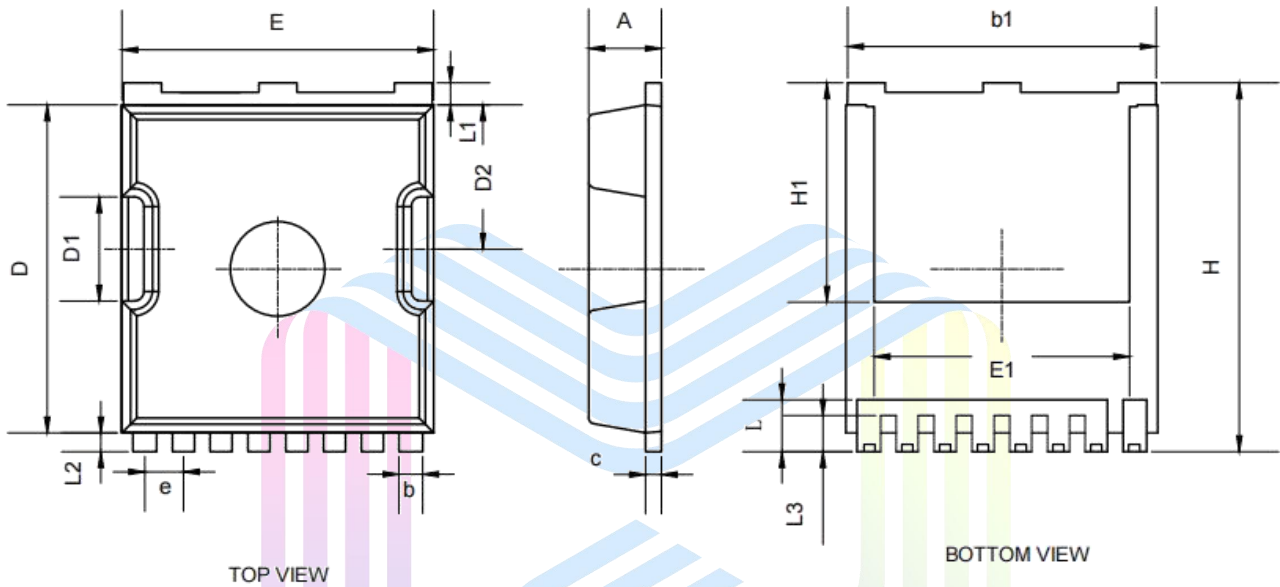
## Electrical Characteristics Diagrams



**Figure 7. Capacitance Characteristics**

**Figure 8. Gate Charge Characteristics**

**Figure 9. Power Dissipation**

**Figure 10. Safe Operating Area**

**Figure 11. Normalized Maximum Transient Thermal Impedance**


## Mechanical Dimensions

### TOLL-8 Package Information



COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	MAX
A	2.15	2.45
b	0.60	0.90
b1	9.65	9.95
c	0.40	0.60
D	10.18	10.58
D1	3.15	3.45
D2	4.40	4.70
E	9.70	10.10
E1	8.10REF	
e	1.20BSC	
H	11.48	11.90
H1	6.95REF	
L	1.55	2.10
L1	0.50	0.90
L2	0.48	0.70
L3	1.15 BSC	

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